IC41C4100 IC41LV4100



Document Title

1Mx4 bit Dynamic RAM with EDO Page Mode

Revision History

Revision No History Draft Date Remark

0A Initial Draft September 5,2001

The attached datasheets are provided by ICSI. Integrated Circuit Solution Inc reserve the right to change the specifications and products. ICSI will answer to your questions about device. If you have any questions, please contact the ICSI offices.



1M x 4 (4-MBIT) DYNAMIC RAM WITH EDO PAGE MODE

FEATURES

- Extended Data-Out (EDO) Page Mode access cycle
- TTL compatible inputs and outputs; tristate I/O
- Refresh Interval: 1024 cycles /16 ms
- Refresh Mode: RAS-Only, CAS-before-RAS (CBR), Hidden
- Single power supply: 5V ± 10% (IC41C4100) 3.3V ± 10% (IC41LV4100)
- Industrail Temperature Range -40°C to 85°C

DESCRIPTION

The *ICSI* IC41C4100 and IC41LV4100 is a 1,048,576 x 4-bit high-performance CMOS Dynamic Random Access Memories. The IC41C4100 offer an accelerated cycle access called EDO Page Mode. EDO Page Mode allows 1024 random accesses within a single row with access cycle time as short as 12 ns per 4-bit word.

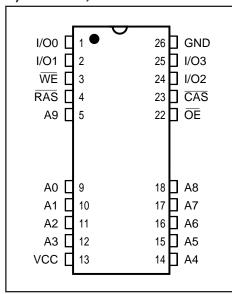
These features make the IC41C4100 and IC41LV4100 ideally suited for, digital signal processing, high-performance audio systems, and peripheral applications.

The IC41C4100 is packaged in a 20-pin 300mil SOJ and 300mil TSOP-2.

KEY TIMING PARAMETERS

Parameter	-35	-50	-60	Unit	
Max. RAS Access Time (trac)	35	50	60	ns	
Max. CAS Access Time (tcac)	10	14	15	ns	
Max. Column Address Access Time (taa)	18	25	30	ns	
Min. EDO Page Mode Cycle Time (tpc)	12	20	25	ns	
Min. Read/Write Cycle Time (trc)	60	90	110	ns	

PIN CONFIGURATION 20 (26) Pin SOJ, TSOP-2

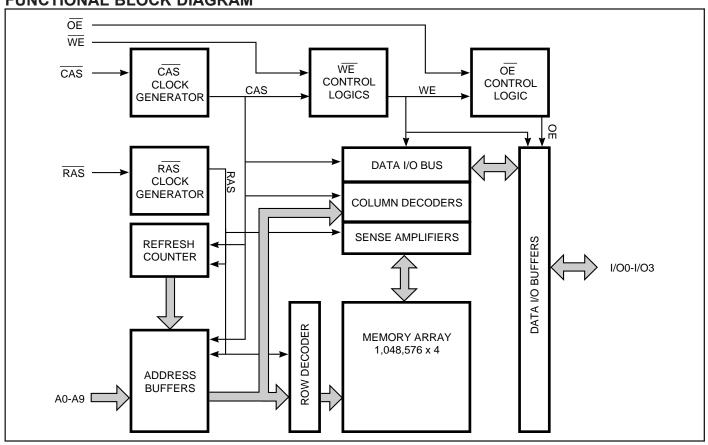


PIN DESCRIPTIONS

A0-A9	Address Inputs
I/O0-3	Data Inputs/Outputs
WE	Write Enable
ŌĒ	Output Enable
RAS	Row Address Strobe
CAS	Column Address Strobe
Vcc	Power
GND	Ground
NC	No Connection



FUNCTIONAL BLOCK DIAGRAM



IC41C4100 IC41LV4100



TRUTH TABLE

Function		RAS	CAS	WE	ŌĒ	Address tr/tc	I/O
Standby		Н	Н	Χ	Χ	Χ	High-Z
Read:		L	L	Н	L	ROW/COL	Dout
Write: (Early Write)		L	L	L	Х	ROW/COL	DIN
Read-Write		L	L	H→L	L→H	ROW/COL	Dout, Din
EDO Page-Mode Read	1st Cycle:	L	H→L	Н	L	ROW/COL	Dout
	2nd Cycle:	L	$H{ ightarrow} L$	Н	L	NA/COL	Douт
	Any Cycle:	L	$L{\rightarrow}H$	Н	L	NA/NA	Dout
EDO Page-Mode Write	1st Cycle:	L	H→L	L	Х	ROW/COL	DIN
	2nd Cycle:	L	$H{ ightarrow} L$	L	Χ	NA/COL	DIN
EDO Page-Mode	1st Cycle:	L	H→L	H→L	L→H	ROW/COL	Dout, Din
Read-Write	2nd Cycle:	L	$H{ ightarrow} L$	$H{ ightarrow} L$	$L{\to}H$	NA/COL	DOUT, DIN
Hidden Refresh	Read	$L\rightarrow H\rightarrow L$	L	Н	L	ROW/COL	Dout
	Write	$L{\rightarrow}H{\rightarrow}L$	L	L	Χ	ROW/COL	DIN
RAS-Only Refresh		L	Н	Х	Х	ROW/NA	High-Z
CBR Refresh		H→L	L	Х	Х	Х	High-Z



Functional Description

The IC41C4100 and IC41LV4100 is a CMOS DRAM optimized for high-speed bandwidth, low power applications. During READ or WRITE cycles, each bit is uniquely addressed through the 20 address bits. These are entered 10 bits (A0-A9) at a time. The row address is latched by the Row Address Strobe (RAS). The column address is latched by the Column Address Strobe (CAS).

Memory Cycle

A memory cycle is initiated by <u>bring RAS LOW</u> and it is terminated by returning both RAS and CAS HIGH. To ensures proper device operation and data integrity any memory cycle, once initiated, must not be ended or aborted before the minimum tras time has expired. A new cycle must not be initiated until the minimum precharge time trp, tcp has elapsed.

Read Cycle

A read cycle is initiated by the falling edge of CAS or OE, whichever occurs last, while holding WE HIGH. The column address must be held for a minimum time specified by tar. Data Out becomes valid only when trac, tar, tar, tar, and toe are all satisfied. As a result, the access time is dependent on the timing relationships between these parameters.

Write Cycle

A write cycle is initiated by the falling edge of \overline{CAS} and \overline{WE} , whichever occurs last. The <u>input</u> data must be valid at or before the falling edge of \overline{CAS} or \overline{WE} , whichever occurs first.

Refresh Cycle

To retain data, 1024 refresh cycles are required in each 16 ms period. There are two ways to refresh the memory.

- By clocking each of the 1024 row addresses (A0 through A9) with RAS at least <u>once</u> every 16 ms. Any read, write, read-modify-write or RAS-only cycle refreshes the addressed row.
- Using a CAS-before-RAS refresh cycle. CAS-before-RAS refresh is activated by the falling edge of RAS, while holding CAS LOW. In CAS-before-RAS refresh cycle, an internal 10-bit counter provides the row addresses and the external address inputs are ignored.

CAS-before-RAS is a refresh-only mode and no data access or device selection is allowed. Thus, the output remains in the High-Z state during the cycle.

Extended Data Out Page Mode

EDO page mode operation permits all 1024 columns within a selected row to be randomly accessed at a high data rate.

In EDO page mode read cycle, the data-out is held to the next CAS cycle's falling edge, instead of the rising edge. For this reason, the valid data output time in EDO page mode is extended compared with the fast page mode. In the fast page mode, the valid data output time becomes shorter as the CAS cycle time becomes shorter. Therefore, in EDO page mode, the timing margin in read cycle is larger than that of the fast page mode even if the CAS cycle time becomes shorter.

In EDO page mode, due to the extended data function, the CAS cycle time can be shorter than in the fast page mode if the timing margin is the same.

The EDO page mode allows both read and write operations during one RAS cycle, but the performance is equivalent to that of the fast page mode in that case.

Power-On

After application of the Vcc supply, an initial pause of 200 µs is required followed by a minimum of eight initialization cycles (any combination of cycles containing a RAS signal).

During power-on, it is recommended that RAS track with Vcc or be held at a valid V_{IH} to avoid current surges.



ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Parameters		Rating	Unit
VT	Voltage on Any Pin Relative to GND	5V	-1.0 to +7.0	V
		3.3V	-0.5 to $+4.6$	
Vcc	Supply Voltage	5V	-1.0 to +7.0	V
		3.3V	-0.5 to $+4.6$	
Іоит	Output Current		50	mA
Po	Power Dissipation		1	W
TA	Commercial Operation Temperature		0 to +70	°C
	Industrial Operationg Temperature		-40 to +85	°C
Тѕтс	Storage Temperature		-55 to +125	°C

Note:

RECOMMENDED OPERATING CONDITIONS (Voltages are referenced to GND.)

Symbol	Parameter		Min.	Тур.	Max.	Unit
Vcc	Supply Voltage	5V	4.5	5.0	5.5	V
		3.3V	3.0	3.3	3.6	
VIH	Input High Voltage	5V	2.4	_	Vcc + 1.0	V
		3.3V	2.0	_	Vcc + 0.3	
VIL	Input Low Voltage	5V	-1.0	_	0.8	V
		3.3V	-0.3	_	8.0	
TA	Commercial Ambient Temperature		0	_	70	°C
	Industrial Ambient Temperature		-40	_	85	°C

CAPACITANCE^(1,2)

Symbol	Parameter	Max.	Unit
CIN1	Input Capacitance: A0-A9	5	pF
CIN2	Input Capacitance: RAS, CAS, WE, OE	7	pF
Сю	Data Input/Output Capacitance: I/O0-I/O3	7	pF

Notes:

- 1. Tested initially and after any design or process changes that may affect these parameters.
- 2. Test conditions: $T_A = 25$ °C, f = 1 MHz.

Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.



ELECTRICAL CHARACTERISTICS(1)

(Recommended Operating Conditions unless otherwise noted.)

Symbol	Parameter	Test Condition		Speed	Min.	Max.	Unit
lı∟	Input Leakage Current	Any input 0V ≤ V _{IN} ≤ V _{CC} Other inputs not under test			-10	10	μΑ
lio	Output Leakage Current	Output is disabled (Hi-Z) 0V ≤ Vouт ≤ Vcc			-10	10	μΑ
Vон	Output High Voltage Level	lон = −2.5 mA			2.4	_	V
Vol	Output Low Voltage Level	IoL =+2.1mA			_	0.4	V
lcc1	Standby Current: TTL	RAS, CAS ≥ VIH	Commerical Industrial Commerical Industrial	5V 5V 3.3V 3.3V		2 3 1 2	mA
Icc2	Standby Current: CMOS	\overline{RAS} , $\overline{CAS} \ge Vcc - 0.2V$		5V 3.3V	_	1 0.5	mA
lcc3	Operating Current: Random Read/Write ^(2,3,4) Average Power Supply Current	RAS, CAS, Address Cycling, trc = tro	(min.)	-35 -50 -60	_	110 95 85	mA
Icc4	Operating Current: EDO Page Mode ^(2,3,4) Average Power Supply Current	$\overline{RAS} = V_{IL}, \overline{CAS},$ Cycling tpc = tpc (min.)		-35 -50 -60		90 80 70	mA
lcc5	Refresh Current: RAS-Only ^(2,3) Average Power Supply Current	\overline{RAS} Cycling, $\overline{CAS} \ge VIH$ trc = trc (min.)		-35 -50 -60	_	110 95 85	mA
Icc6	Refresh Current: CBR ^(2,3,5) Average Power Supply Current	RAS, CAS Cycling trc = trc (min.)		-35 -50 -60	_	110 95 85	mA

Notes:

^{1.} An initial pause of 200 µs is required after power-up followed by eight RAS refresh cycles (RAS-Only or CBR) before proper device operation is assured. The eight RAS cycles wake-up should be repeated any time the tree refresh requirement is exceeded.

^{2.} Dependent on cycle rates.

^{3.} Specified values are obtained with minimum cycle time and the output open.

^{4.} Column-address is changed once each EDO page cycle.

^{5.} Enables on-chip refresh and address counters.



AC CHARACTERISTICS(1,2,3,4,5,6)

(Recommended Operating Conditions unless otherwise noted.)

			35	-	-50		-60	
Symbol	Parameter		Max.		Max.		Max.	Units
trc	Random READ or WRITE Cycle Time	60	_	90	_	110	_	ns
t rac	Access Time from RAS(6, 7)	_	35		50	_	60	ns
tcac	Access Time from CAS(6, 8, 15)	_	10	_	14	_	15	ns
t AA	Access Time from Column-Address ⁽⁶⁾	_	18	_	25	_	30	ns
tras	RAS Pulse Width	35	10K	50	10K	60	10K	ns
t RP	RAS Precharge Time	20	_	30	_	40	_	ns
tcas	CAS Pulse Width(26)	6	10K	8	10K	10	10K	ns
tcp	CAS Precharge Time(9, 25)	5	_	8	_	10	_	ns
tcsH	CAS Hold Time (21)	35	_	50	_	60	_	ns
trcd	RAS to CAS Delay Time(10, 20)	11	28	19	36	20	45	ns
tasr	Row-Address Setup Time	0	_	0	_	0	_	ns
t rah	Row-Address Hold Time	6	_	8	_	10	_	ns
tasc	Column-Address Setup Time(20)	0	_	0	_	0	_	ns
t CAH	Column-Address Hold Time(20)	6	_	8	_	10	_	ns
tar	Column-Address Hold Time (referenced to RAS)	30	_	40	_	40	_	ns
t rad	RAS to Column-Address Delay Time(11)	10	20	14	25	15	30	ns
t ral	Column-Address to RAS Lead Time	18	_	25	_	30	_	ns
t rpc	RAS to CAS Precharge Time	0	_	0	_	0	_	ns
trsh	RAS Hold Time(27)	8	_	14	_	15	_	ns
tclz	CAS to Output in Low-Z ^(15, 29)	3	_	3	_	3	_	ns
tcrp	CAS to RAS Precharge Time(21)	5	_	5	_	5	_	ns
top	Output Disable Time(19, 28, 29)	3	12	3	12	3	12	ns
toe	Output Enable Time(15, 16)	0	10	0	15	_	15	ns
toehc	OE HIGH Hold Time from CAS HIGH	10	_	10	_	10	_	ns
toep	OE HIGH Pulse Width	10	_	10	_	10	_	ns
toes	OE LOW to CAS HIGH Setup Time	5	_	5	_	5	_	ns
trcs	Read Command Setup Time(17, 20)	0	_	0	_	0	_	ns
t rrh	Read Command Hold Time (referenced to RAS) ⁽¹²⁾	0	_	0	_	0	_	ns
t RCH	Read Command Hold Time (referenced to CAS)(12, 17, 21)	0	_	0	_	0	_	ns
twch	Write Command Hold Time ^(17, 27)	5	_	8	_	10	_	ns
twcr	Write Command Hold Time (referenced to RAS)(17)	30	_	40	_	50	_	ns
twp	Write Command Pulse Width(17)	5	_	8	_	10	_	ns
twpz	WE Pulse Widths to Disable Outputs	10	_	10	_	10	_	ns
trwL	Write Command to RAS Lead Time(17)	8		14		15		ns
tcwl	Write Command to CAS Lead Time(17,21)	8	_	14	_	15		ns
twcs	Write Command Setup Time(14, 17, 20)	0		0		0		ns
tour tour	Data-in Hold Time (referenced to RAS)	30		40		40		ns



AC CHARACTERISTICS (Continued)(1,2,3,4,5,6)

(Recommended Operating Conditions unless otherwise noted.)

		;	35	4	50	-	60	
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Units
tach	Column-Address Setup Time to CAS Precharge during WRITE Cycle	15	_	15	_	15	_	ns
tоен	OE Hold Time from WE during READ-MODIFY-WRITE cycle ⁽¹⁸⁾	8	_	10	_	15	_	ns
tos	Data-In Setup Time(15, 22)	0	_	0	_	0	_	ns
ton	Data-In Hold Time(15, 22)	6	_	8	_	10	_	ns
trwc	READ-MODIFY-WRITE Cycle Time	80	_	125	_	140	_	ns
trwd	RAS to WE Delay Time during READ-MODIFY-WRITE Cycle ⁽¹⁴⁾	45	_	70	_	80	_	ns
tcwd	CAS to WE Delay Time(14, 20)	25	_	34	_	36	_	ns
tawd	Column-Address to WE Delay Time(14)	30	_	42	_	49	_	ns
tpc	EDO Page Mode READ or WRITE Cycle Time ⁽²⁴⁾	12	_	20	_	25	_	ns
trasp	RAS Pulse Width in EDO Page Mode	35	100K	50	100K	50	100K	ns
t CPA	Access Time from CAS Precharge(15)	_	21	_	27	_	34	ns
tPRWC	EDO Page Mode READ-WRITE Cycle Time ⁽²⁴⁾	40	_	47	_	56	_	ns
tсон	Data Output Hold after CAS LOW	5	_	5	_	5	_	ns
toff	Output Buffer Turn-Off Delay from CAS or RAS ^(13,15,19,29)	3	15	3	15	3	15	ns
twnz	Output Disable Delay from WE	3	15	3	15	3	15	ns
tclch	Last CAS going LOW to First CAS returning HIGH ⁽²³⁾	10	_	10	_	10	_	ns
tcsr	CAS Setup Time (CBR REFRESH)(30, 20)	8	_	10	_	10	_	ns
tchr	CAS Hold Time (CBR REFRESH)(30, 21)	8	_	10	_	10	_	ns
tord	OE Setup Time prior to RAS during HIDDEN REFRESH Cycle	0	_	0	_	0	_	ns
tref	Refresh Period (512 Cycles)	_	8	8	_	8	_	ms
tτ	Transition Time (Rise or Fall)(2,3)	1	50	1	50	1	50	ns

AC TEST CONDITIONS

Output load: Two TTL Loads and 50 pF ($Vcc = 5.0V \pm 10\%$)

One TTL Load and 50 pF (Vcc = 3.3V ±10%)

Input timing reference levels: $V_{IH} = 2.4V$, $V_{IL} = 0.8V$ ($V_{CC} = 5.0V \pm 10\%$);

 $V_{IH} = 2.0V$, $V_{IL} = 0.8V$ ($V_{CC} = 3.3V \pm 10\%$)

Output timing reference levels: VOH = 2.0V, VOL = 0.8V ($VCC = 5V \pm 10\%$, $3.3V \pm 10\%$)

IC41C4100 IC41LV4100

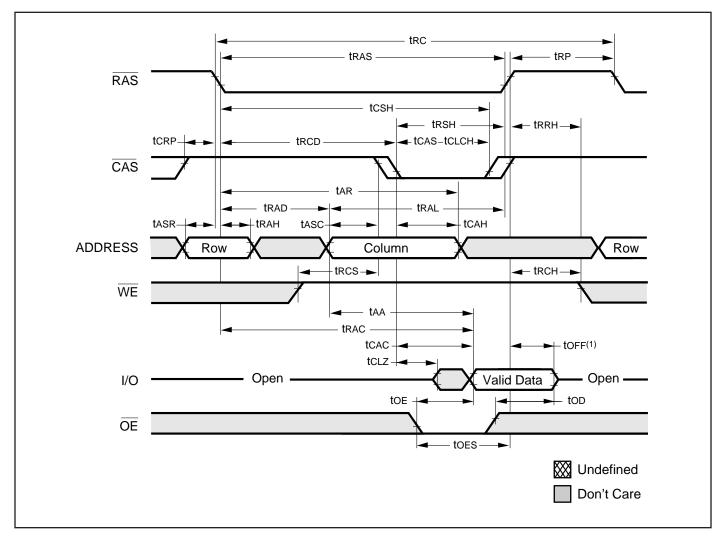


Notes:

- 1. An initial pause of 200 µs is required after power-up followed by eight RAS refresh cycle (RAS-Only or CBR) before proper device operation is assured. The eight RAS cycles wake-up should be repeated any time the tree refresh requirement is exceeded.
- 2. Vih (MIN) and Vil (MAX) are reference levels for measuring timing of input signals. Transition times, are measured between Vih and Vil (or between Vil and Vih) and assume to be 1 ns for all inputs.
- 3. In addition to meeting the transition rate specification, all input signals must transit between V_{IH} and V_{IL} (or between V_{IL} and V_{IH}) in a monotonic manner.
- 4. If \overline{CAS} and $\overline{RAS} = V_{IH}$, data output is High-Z.
- 5. If $\overline{CAS} = V_{IL}$, data output may contain data from the last valid READ cycle.
- 6. Measured with a load equivalent to one TTL gate and 50 pF.
- 7. Assumes that tRCD ≤ tRCD (MAX). If tRCD is greater than the maximum recommended value shown in this table, tRAC will increase by the amount that tRCD exceeds the value shown.
- 8. Assumes that $trcd \ge trcd (MAX)$.
- 9. If $\overline{\text{CAS}}$ is LOW at the falling edge of $\overline{\text{RAS}}$, data out will be maintained from the previous cycle. To initiate a new cycle and clear the data output buffer, $\overline{\text{CAS}}$ and $\overline{\text{RAS}}$ must be pulsed for tcp.
- 10. Operation with the tRCD (MAX) limit ensures that tRAC (MAX) can be met. tRCD (MAX) is specified as a reference point only; if tRCD is greater than the specified tRCD (MAX) limit, access time is controlled exclusively by tCAC.
- 11. Operation within the trad (MAX) limit ensures that trad (MAX) can be met. trad (MAX) is specified as a reference point only; if trad is greater than the specified trad (MAX) limit, access time is controlled exclusively by trad.
- 12. Either trich or trich must be satisfied for a READ cycle.
- 13. toff (MAX) defines the time at which the output achieves the open circuit condition; it is not a reference to Voh or Vol.
- 14. twcs, trwb, tawb and tcwb are restrictive operating parameters in LATE WRITE and READ-MODIFY-WRITE cycle only. If twcs ≥ twcs (MIN), the cycle is an EARLY WRITE cycle and the data output will remain open circuit throughout the entire cycle. If trwb ≥ trwb (MIN), tawb ≥ tawb (MIN) and tcwb ≥ tcwb (MIN), the cycle is a READ-WRITE cycle and the data output will contain data read from the selected cell. If neither of the above conditions is met, the state of I/O (at access time and until CAS and RAS or OE go back to Vih) is indeterminate. OE held HIGH and WE taken LOW after CAS goes LOW result in a LATE WRITE (OE-controlled) cycle.
- 15. Output parameter (I/O) is referenced to corresponding CAS input.
- 16. During a READ cycle, if \overline{OE} is LOW then taken HIGH before \overline{CAS} goes HIGH, I/O goes open. If \overline{OE} is tied permanently LOW, a LATE WRITE or READ-MODIFY-WRITE is not possible.
- 17. Write command is defined as \overline{WE} going low.
- 18. LATE WRITE and READ-MODIFY-WRITE cycles must have both top and toeh met (OE HIGH during WRITE cycle) in order to ensure that the output buffers will be open during the WRITE cycle. The I/Os will provide the previously written data if CAS remains LOW and OE is taken back to LOW after toeh is met.
- 19. The I/Os are in open during READ cycles once too or toff occur.
- 20. The first $\chi \overline{\text{CAS}}$ edge to transition LOW.
- 21. The last $\chi \overline{\text{CAS}}$ edge to transition HIGH.
- 22. These parameters are referenced to $\overline{\text{CAS}}$ leading edge in EARLY WRITE cycles and $\overline{\text{WE}}$ leading edge in LATE WRITE or READ-MODIFY-WRITE cycles.
- 23. Last falling $\chi \overline{CAS}$ edge to first rising $\chi \overline{CAS}$ edge.
- 24. Last rising $\chi \overline{CAS}$ edge to next cycle's last rising $\chi \overline{CAS}$ edge.
- 25. Last rising $\chi \overline{CAS}$ edge to first falling $\chi \overline{CAS}$ edge.
- 26. Each $\chi \overline{\text{CAS}}$ must meet minimum pulse width.
- 27. Last $\chi \overline{\text{CAS}}$ to go LOW.
- 28. I/Os controlled, regardless CAS.
- 29. The 3 ns minimum is a parameter guaranteed by design.
- 30. Enables on-chip refresh and address counters.



READ CYCLE

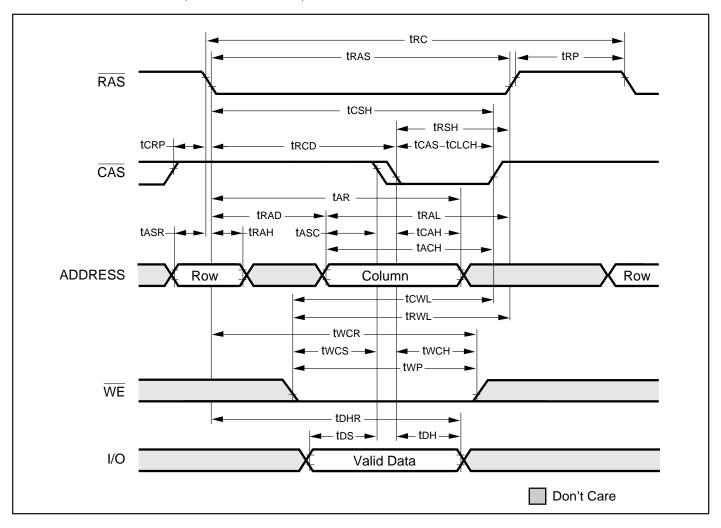


Note:

1. toff is referenced from rising edge of RAS or CAS, whichever occurs last.

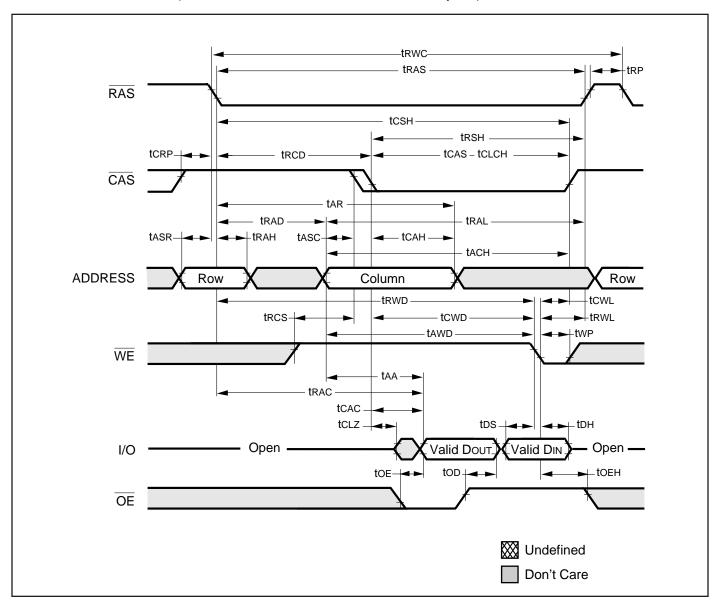


EARLY WRITE CYCLE (OE = DON'T CARE)



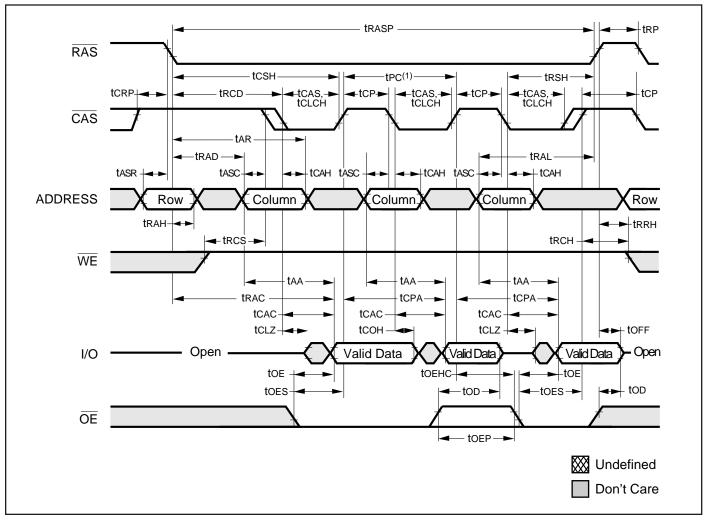


READ WRITE CYCLE (LATE WRITE and READ-MODIFY-WRITE Cycles)





EDO-PAGE-MODE READ CYCLE

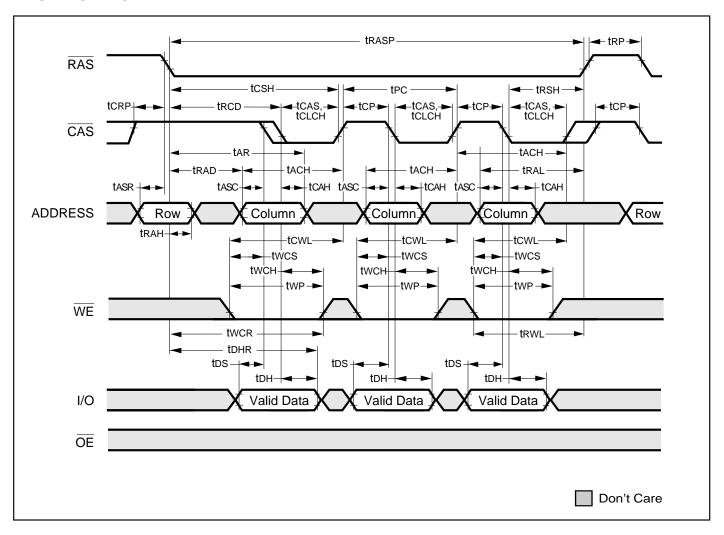


Note:

1. tPC can be measured from falling edge of CAS to falling edge of CAS, or from rising edge of CAS to rising edge of CAS. Both measurements must meet the tPC specifications.

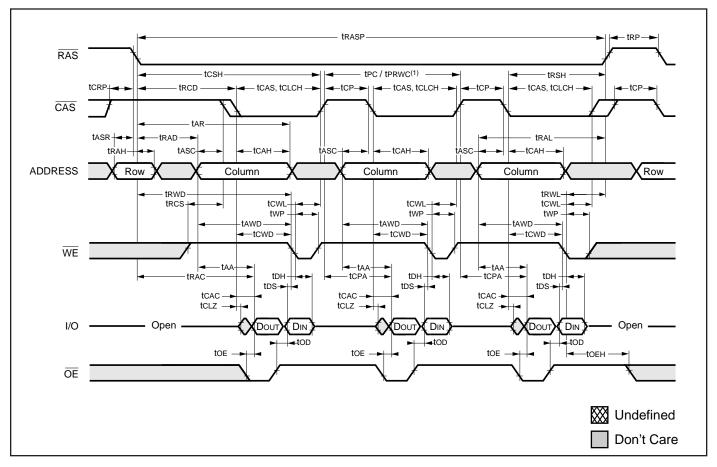


EDO-PAGE-MODE EARLY-WRITE CYCLE





EDO-PAGE-MODE READ-WRITE CYCLE (LATE WRITE and READ-MODIFY WRITE Cycles)

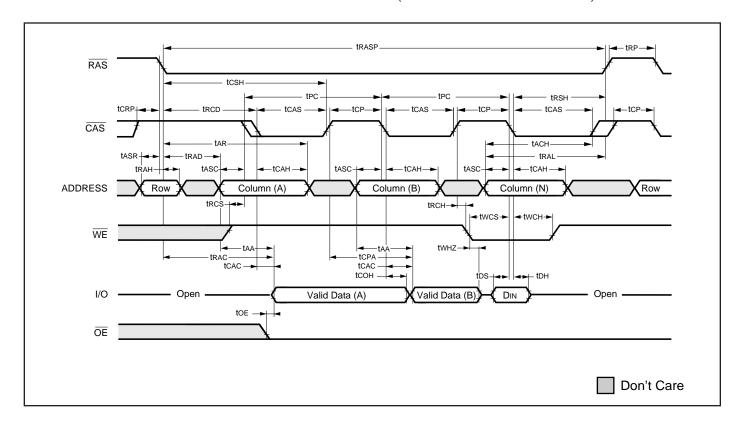


Note

1. tec is for LATE write cycles only. tec can be measured from falling edge of $\overline{\text{CAS}}$ to falling edge of $\overline{\text{CAS}}$, or from rising edge of $\overline{\text{CAS}}$. Both measurements must meet the tec specifications.



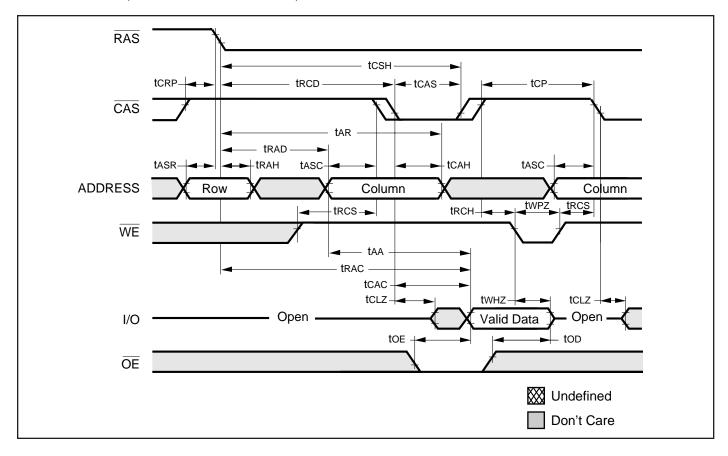
EDO-PAGE-MODE READ-EARLY-WRITE CYCLE (Psuedo READ-MODIFY WRITE)



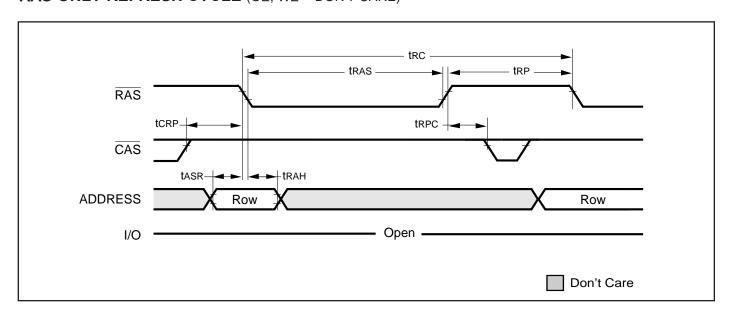


AC WAVEFORMS

READ CYCLE (With WE-Controlled Disable)

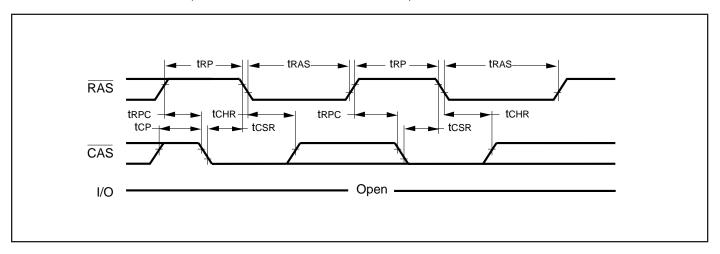


RAS-ONLY REFRESH CYCLE (OE, WE = DON'T CARE)

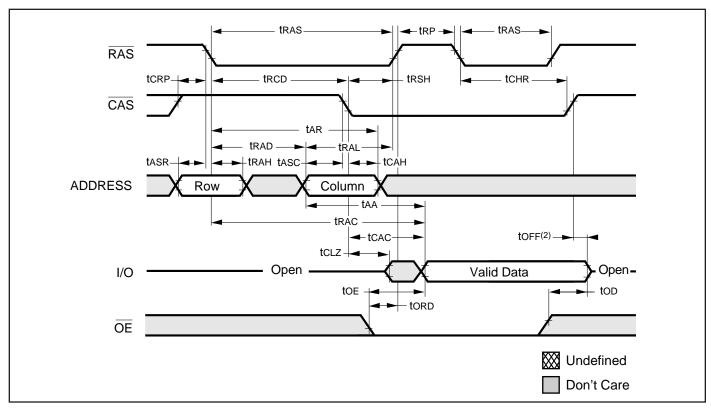




CBR REFRESH CYCLE (Addresses; \overline{WE} , \overline{OE} = DON'T CARE)



HIDDEN REFRESH CYCLE(1) (WE = HIGH; OE = LOW)



Notes:

- 1. A Hidden Refresh may also be performed after a Write Cycle. In this case, \overline{WE} = LOW and \overline{OE} = HIGH. 2. toff is referenced from rising edge of \overline{RAS} or \overline{CAS} , whichever occurs last.



ORDERING INFORMATION IC41C4100

Commercial Range: 0°C to 70°C

ORDERING INFORMATION: IC41LV4100

Commercial Range: 0°C to 70°C

Speed (ns)	Order Part No.	PacJage	Speed (ns)	Order Part No.	Package
35	IC41C4100-35J IS41C4100-35T	300mil SOJ 300mil TSOP-2	35	IC41LV4100-35J IC41LV4100-35T	300mil SOJ 300mil TSOP-2
50	IC41C4100-50J IC41C4100-50T	300mil SOJ 300mil TSOP-2	50	IC41LV4100-50J IC41LV4100-50T	300mil SOJ 300mil TSOP-2
60	IC41C4100-60J IC41C4100-60T	300mil SOJ 300mil TSOP-2	60	IC41LV4100-60J IC41LV4100-60T	300mil SOJ 300mil TSOP-2

Industrial Range: -40°C to 85°C Industrial Range: -40°C to 85°C

Speed (ns)	Order Part No.	Package	Speed (ns)	Order Part No.	Package
35	IC41C4100-35JI	300mil SOJ	35	IC41LV4100-35J	300mil SOJ
	IC41C4100-35TI	300mil TSOP-2		IC41LV4100-35T	300mil TSOP-2
50	IC41C4100-50JI	300mil SOJ	50	IC41LV4100-50JI	300mil SOJ
	IC41C4100-50TI	300mil TSOP-2		IC41LV4100-50TI	300mil TSOP-2
60	IC41C4100-60JI	300mil SOJ	60	IC41LV4100-60JI	300mil SOJ
	IC41C4100-60TI	300mil TSOP-2		IC41LV4100-60TI	300mil TSOP-2





Integrated Circuit Solution Inc.

HEADQUARTER:

NO.2, TECHNOLOGY RD. V, SCIENCE-BASED INDUSTRIAL PARK,

HSIN-CHU, TAIWAN, R.O.C.

TEL: 886-3-5780333 Fax: 886-3-5783000

BRANCH OFFICE:

7F, NO. 106, SEC. 1, HSIN-TAI 5TH ROAD,

HSICHIH TAIPEI COUNTY, TAIWAN, R.O.C.

TEL: 886-2-26962140 FAX: 886-2-26962252

http://www.icsi.com.tw